

ABSTRACT

The present disclosure relates to a sealing material composition with plasma resistance for use in semiconductor manufacturing equipment, a sealing material, a gate seal for semiconductor manufacturing equipment, and semiconductor manufacturing equipment, wherein the sealing material composition includes a silicone polymer and a vulcanizing agent, the silicone polymer containing a polysiloxane-based compound having an unsubstituted or substituted aromatic monovalent hydrocarbon group in a side chain. According to the present disclosure, provided is a sealing material composition, which can be used in low-temperature environments and has plasma resistance, and from which a sealing material for semiconductor manufacturing equipment can be produced by using relatively inexpensive materials.